

MOSFET

OptiMOS™ 6 Power-Transistor, 120 V

Features

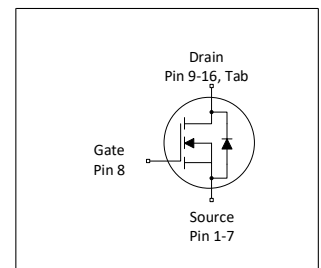
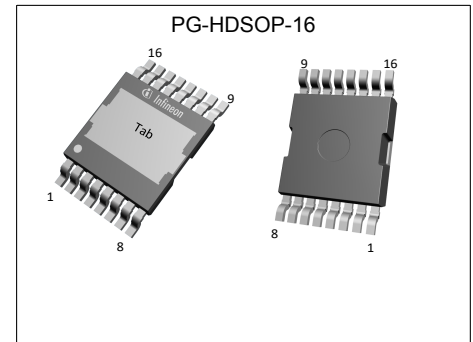
- N-channel, normal level
- Very low on-resistance $R_{DS(on)}$
- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Very low reverse recovery charge (Q_{rr})
- High avalanche energy rating
- 175°C operating temperature
- Optimized for high frequency switching and Top side cooling
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21
- MSL 1 classified according to J-STD-020

Product validation

Fully qualified according to JEDEC for Industrial Applications

Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	120	V
$R_{DS(on),max}$	2.6	m Ω
I_D	222	A
Q_{oss}	166	nC
Q_G (0V...10V)	70	nC
Q_{rr} (1000A/ μ s)	245	nC



RoHS

Type / Ordering Code	Package	Marking	Related Links
IPTC026N12NM6	PG-HDSOP-16	026N12N6	-

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1 Maximum ratings

at $T_A=25\text{ °C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D	-	-	222 157 143 26	A	$V_{GS}=10\text{ V}$, $T_C=25\text{ °C}$ $V_{GS}=10\text{ V}$, $T_C=100\text{ °C}$ $V_{GS}=8\text{ V}$, $T_C=100\text{ °C}$ $V_{GS}=10\text{ V}$, $T_A=25\text{ °C}$, $R_{thJA}=40\text{ °C/W}^2)$
Pulsed drain current ³⁾	$I_{D,pulse}$	-	-	888	A	$T_A=25\text{ °C}$
Avalanche current, single pulse ⁴⁾	I_{AS}	-	-	115	A	$T_C=25\text{ °C}$
Avalanche energy, single pulse	E_{AS}	-	-	623	mJ	$I_D=62\text{ A}$, $R_{GS}=25\text{ }\Omega$
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	278 3.8	W	$T_C=25\text{ °C}$ $T_A=25\text{ °C}$, $R_{thJA}=40\text{ °C/W}^2)$
Operating and storage temperature	T_j , T_{stg}	-55	-	175	°C	-

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, top	R_{thJC}	-	-	0.54	°C/W	-
Thermal characterization parameter, junction to lead (Pin 1-7) ⁵⁾	Ψ_{JL}	-	9	-	°C/W	-
Thermal characterization parameter, junction to lead (Pin 9-16) ⁵⁾	Ψ_{JL}	-	3	-	°C/W	-
Thermal resistance, junction - ambient ²⁾	R_{thJA}	-	40	-	-	-

¹⁾ Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

³⁾ See Diagram 3 for more detailed information

⁴⁾ See Diagram 13 for more detailed information

⁵⁾ Ψ_{JL} is a temperature characterization parameter according to JESD51-12 referring to the temperature difference between junction and leads in the case of natural convection. It can be used to estimate the component junction temperature in the application by measuring the temperature at the leads in the stated application environment

3 Electrical characteristics

at $T_j=25\text{ °C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	120	-	-	V	$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$
Gate threshold voltage	$V_{GS(th)}$	2.6	3.1	3.6	V	$V_{DS}=V_{GS}$, $I_D=169\text{ }\mu\text{A}$
Zero gate voltage drain current	I_{DSS}	-	0.1 10	1 100	μA	$V_{DS}=100\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$ $V_{DS}=100\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=125\text{ °C}$
Gate-source leakage current	I_{GSS}	-	10	100	nA	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	2.3 2.5	2.6 3.13	$\text{m}\Omega$	$V_{GS}=10\text{ V}$, $I_D=115\text{ A}$ $V_{GS}=8\text{ V}$, $I_D=58\text{ A}$
Gate resistance	R_G	0.5	1.0	1.5	Ω	-
Transconductance	g_{fs}	85	170	-	S	$ V_{DS} \geq 2 I_D R_{DS(on)max}$, $I_D=115\text{ A}$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	5000	6500	pF	$V_{GS}=0\text{ V}$, $V_{DS}=60\text{ V}$, $f=1\text{ MHz}$
Output capacitance ¹⁾	C_{oss}	-	1500	2000	pF	$V_{GS}=0\text{ V}$, $V_{DS}=60\text{ V}$, $f=1\text{ MHz}$
Reverse transfer capacitance ¹⁾	C_{rss}	-	27	47	pF	$V_{GS}=0\text{ V}$, $V_{DS}=60\text{ V}$, $f=1\text{ MHz}$
Turn-on delay time	$t_{d(on)}$	-	17.1	-	ns	$V_{DD}=60\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=58\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$
Rise time	t_r	-	9.7	-	ns	$V_{DD}=60\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=58\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$
Turn-off delay time	$t_{d(off)}$	-	28.0	-	ns	$V_{DD}=60\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=58\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$
Fall time	t_f	-	11.7	-	ns	$V_{DD}=60\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=58\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$

Table 6 Gate charge characteristics²⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	26	34	nC	$V_{DD}=60\text{ V}$, $I_D=58\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate charge at threshold	$Q_{g(th)}$	-	15.5	19.4	nC	$V_{DD}=60\text{ V}$, $I_D=58\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate to drain charge ¹⁾	Q_{gd}	-	15.4	23	nC	$V_{DD}=60\text{ V}$, $I_D=58\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Switching charge	Q_{sw}	-	26	-	nC	$V_{DD}=60\text{ V}$, $I_D=58\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate charge total ¹⁾	Q_g	-	70	88	nC	$V_{DD}=60\text{ V}$, $I_D=58\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate plateau voltage	$V_{plateau}$	-	5.1	-	V	$V_{DD}=60\text{ V}$, $I_D=58\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Output charge ¹⁾	Q_{oss}	-	166	221	nC	$V_{DS}=60\text{ V}$, $V_{GS}=0\text{ V}$

¹⁾ Defined by design. Not subject to production test.

²⁾ See "Gate charge waveforms" for parameter definition

Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	222	A	$T_C=25\text{ °C}$
Diode pulse current	$I_{S,pulse}$	-	-	888	A	$T_C=25\text{ °C}$
Diode forward voltage	V_{SD}	-	0.88	1.0	V	$V_{GS}=0\text{ V}, I_F=115\text{ A}, T_j=25\text{ °C}$
Reverse recovery time ¹⁾	t_{rr}	-	35	70	ns	$V_R=60\text{ V}, I_F=58\text{ A}, di_F/dt=300\text{ A}/\mu\text{s}$
Reverse recovery charge ¹⁾	Q_{rr}	-	85	170	nC	$V_R=60\text{ V}, I_F=58\text{ A}, di_F/dt=300\text{ A}/\mu\text{s}$
Reverse recovery time ¹⁾	t_{rr}	-	30	60	ns	$V_R=60\text{ V}, I_F=58\text{ A}, di_F/dt=1000\text{ A}/\mu\text{s}$
Reverse recovery charge ¹⁾	Q_{rr}	-	245	490	nC	$V_R=60\text{ V}, I_F=58\text{ A}, di_F/dt=1000\text{ A}/\mu\text{s}$

¹⁾ Defined by design. Not subject to production test.

4 Electrical characteristics diagrams

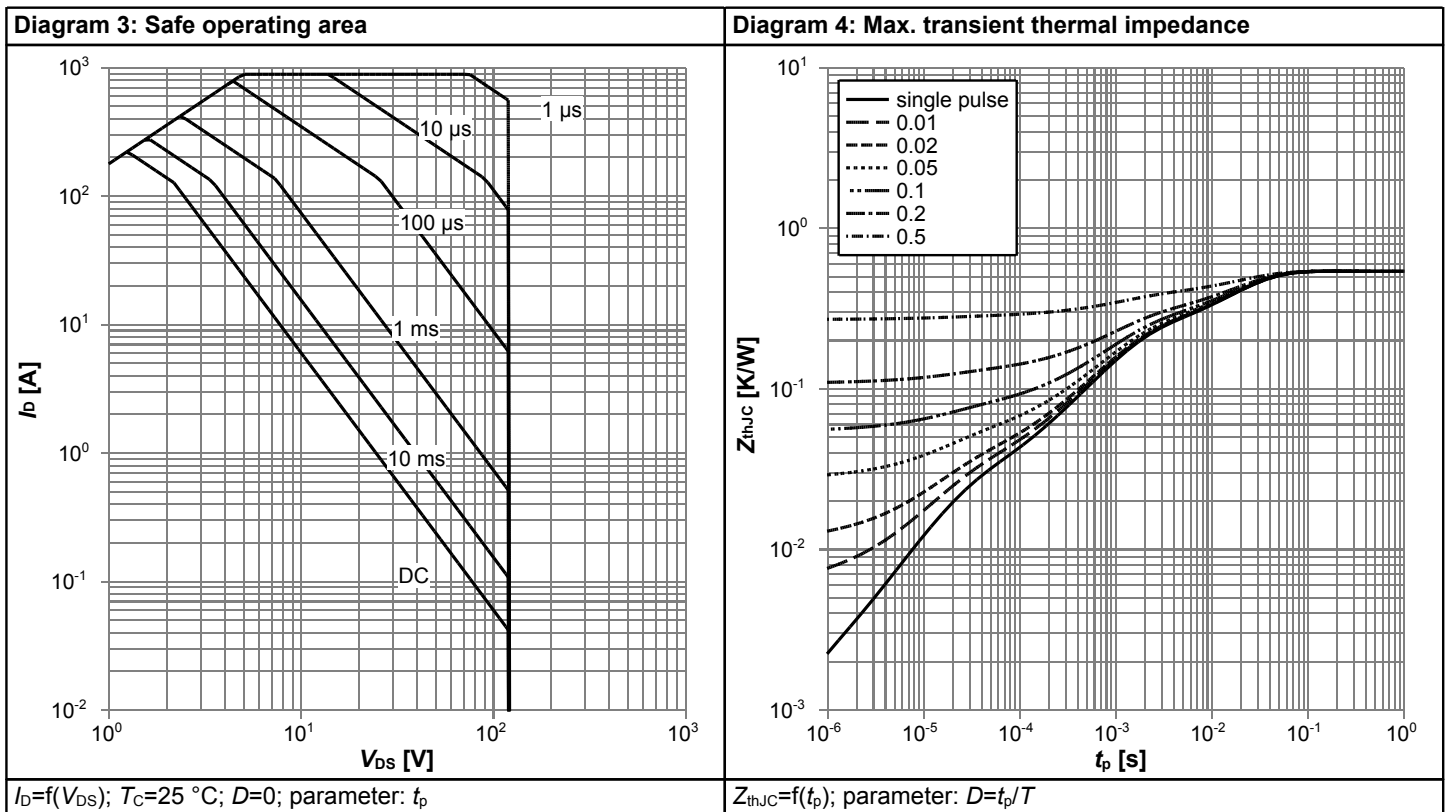
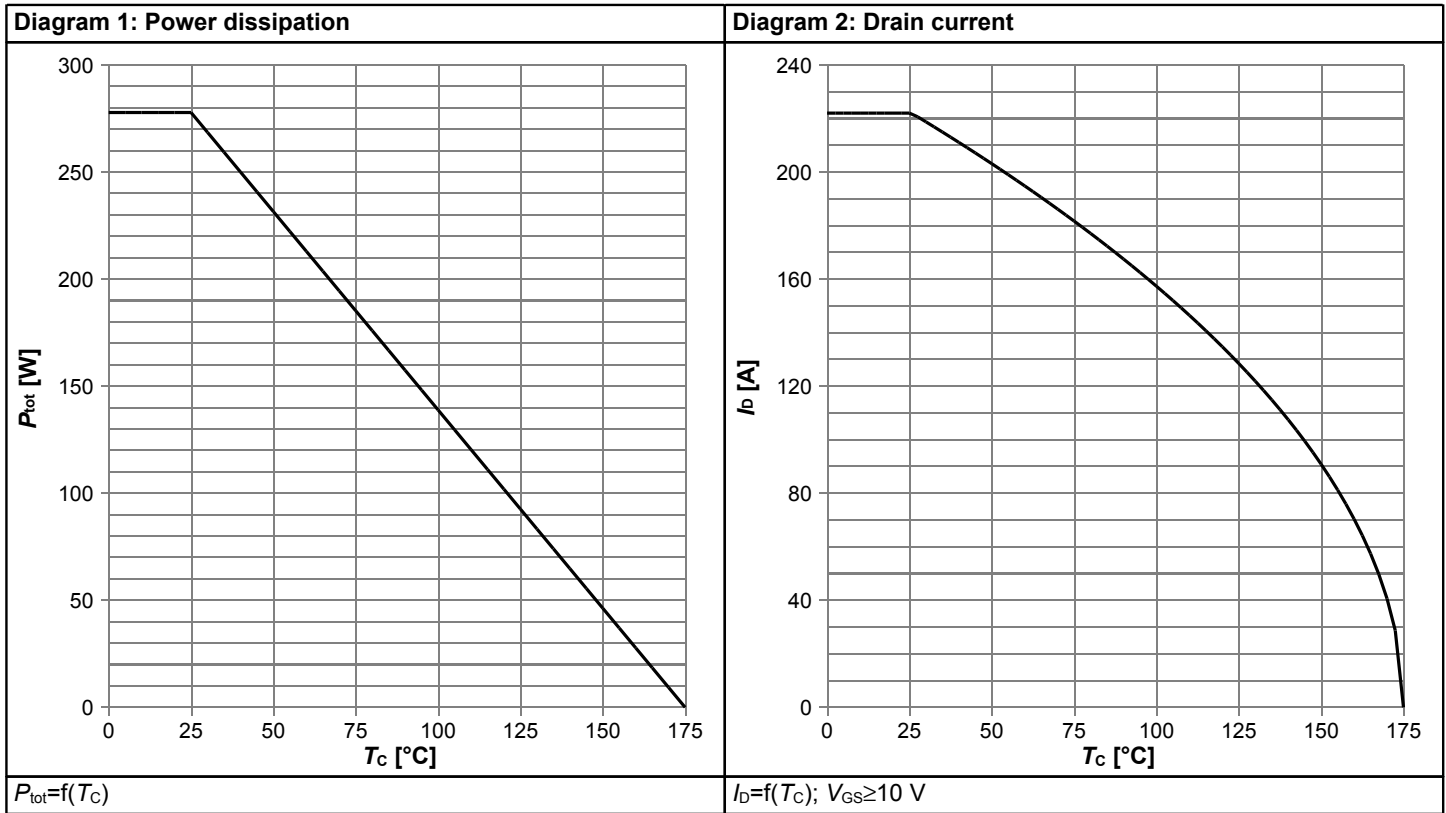
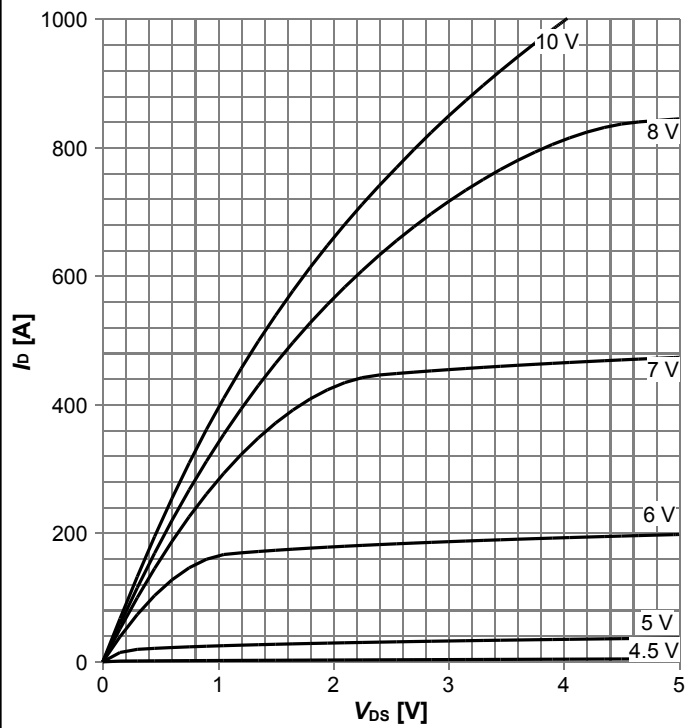
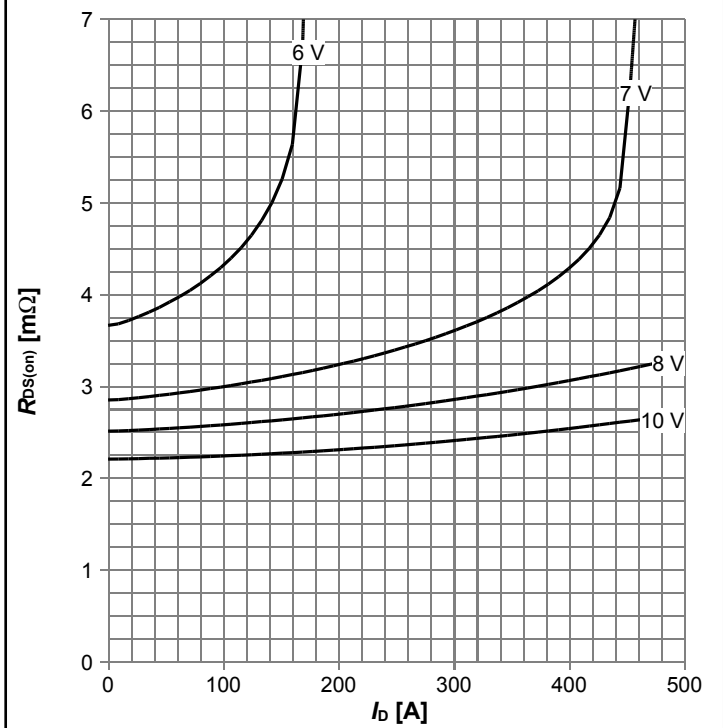


Diagram 5: Typ. output characteristics



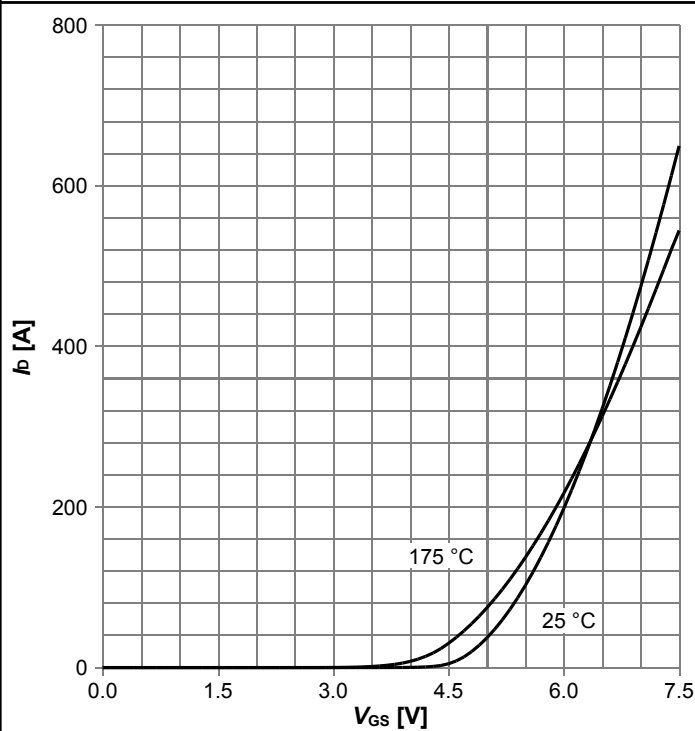
$I_D = f(V_{DS})$, $T_j = 25\text{ °C}$; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



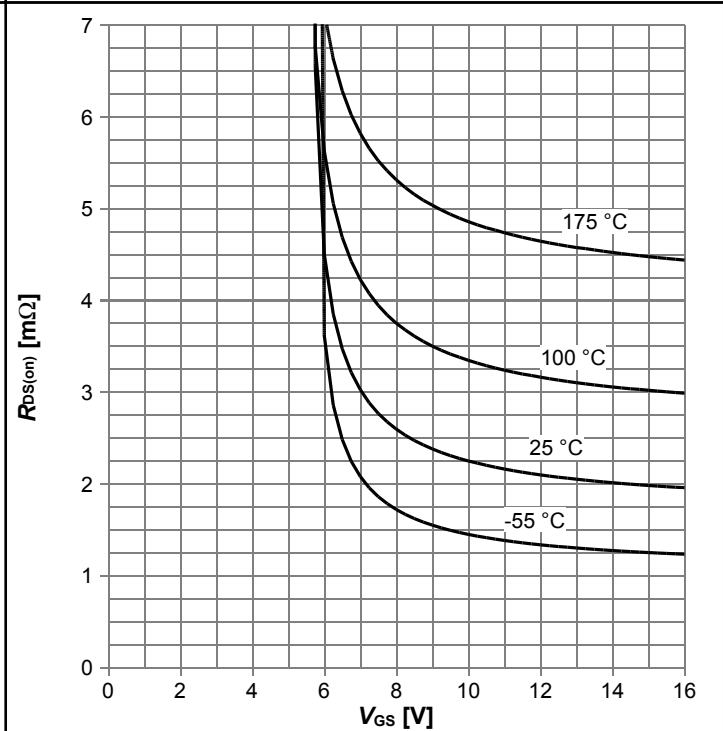
$R_{DS(on)} = f(I_D)$, $T_j = 25\text{ °C}$; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



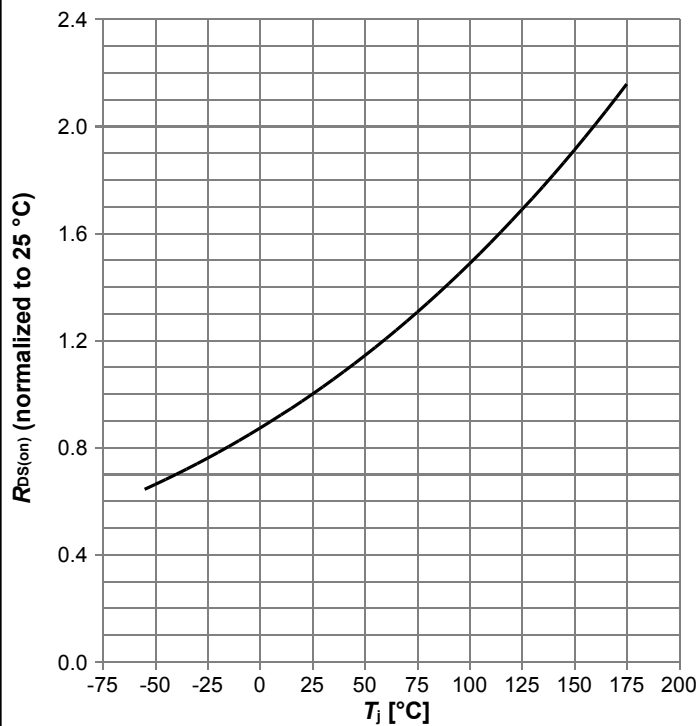
$I_D = f(V_{GS})$, $|V_{DS}| > 2|I_D|R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



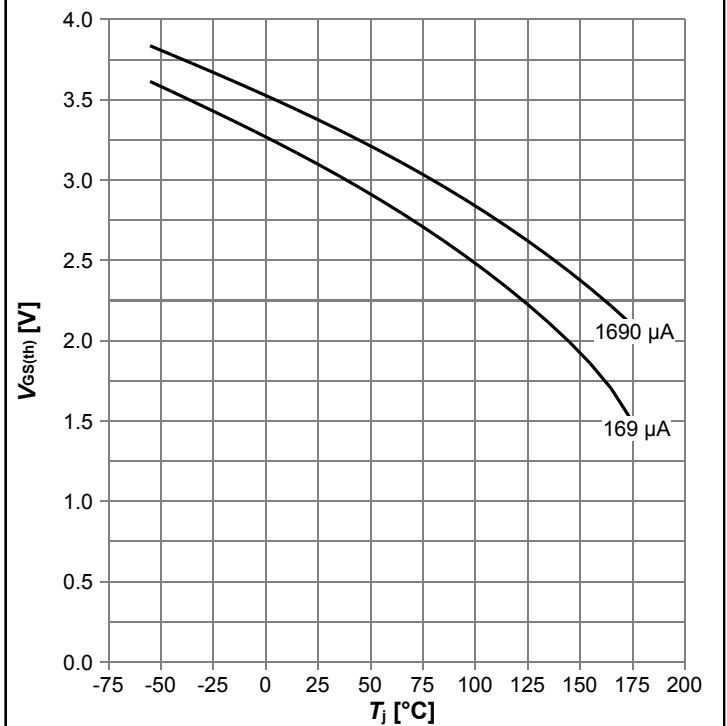
$R_{DS(on)} = f(V_{GS})$, $I_D = 115\text{ A}$; parameter: T_j

Diagram 9: Normalized drain-source on resistance



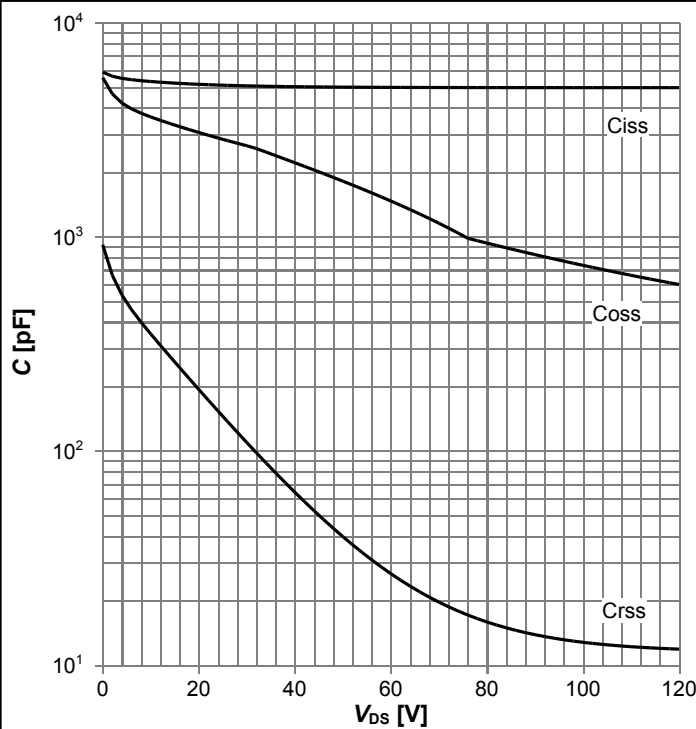
$R_{DS(on)}=f(T_j)$, $I_D=115$ A, $V_{GS}=10$ V

Diagram 10: Typ. gate threshold voltage



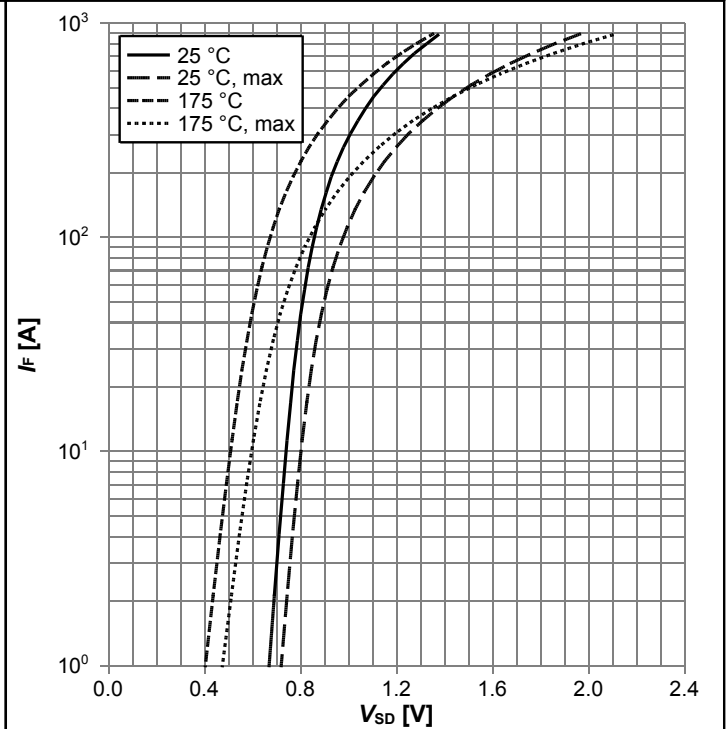
$V_{GS(th)}=f(T_j)$, $V_{GS}=V_{DS}$; parameter: I_D

Diagram 11: Typ. capacitances



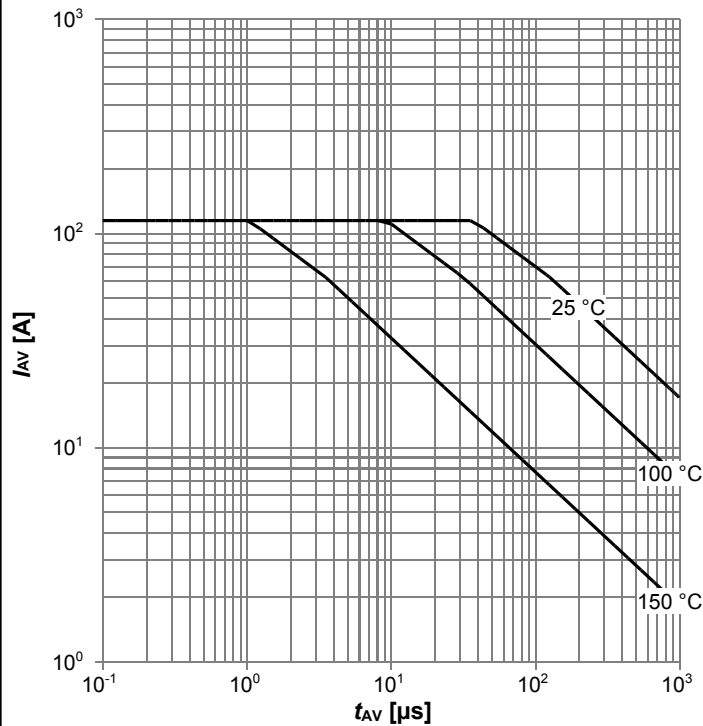
$C=f(V_{DS})$; $V_{GS}=0$ V; $f=1$ MHz

Diagram 12: Forward characteristics of reverse diode



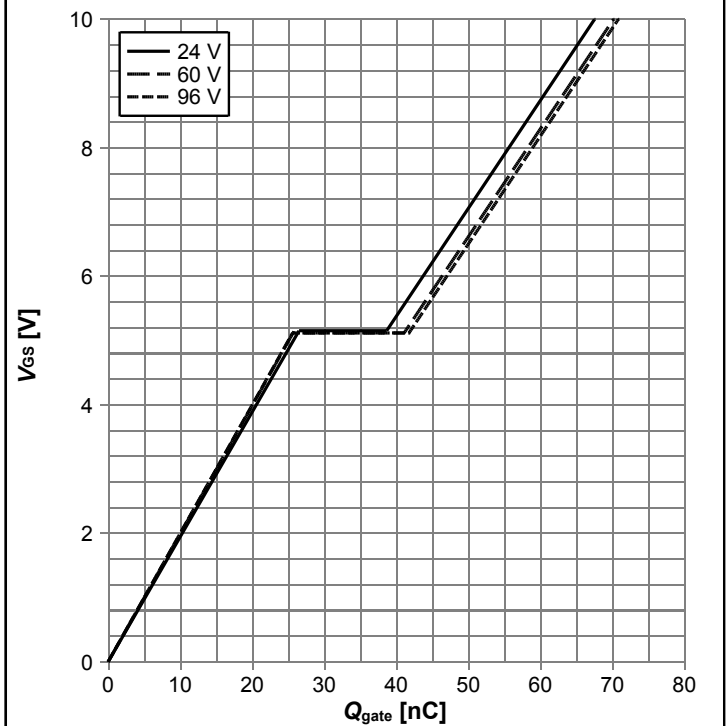
$I_F=f(V_{SD})$; parameter: T_j

Diagram 13: Avalanche characteristics



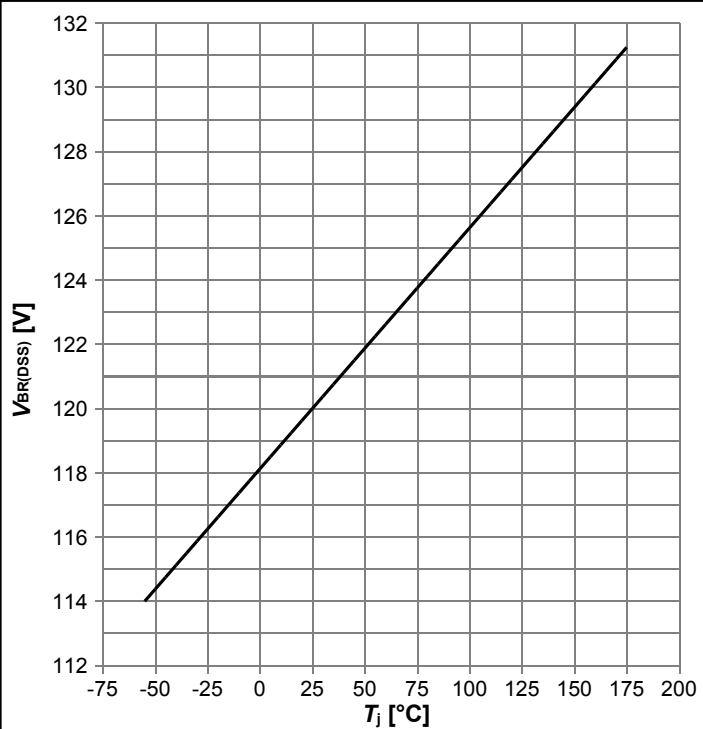
$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$; parameter: $T_{j,start}$

Diagram 14: Typ. gate charge



$V_{GS}=f(Q_{gate}), I_D=115$ A pulsed, $T_j=25$ °C; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage

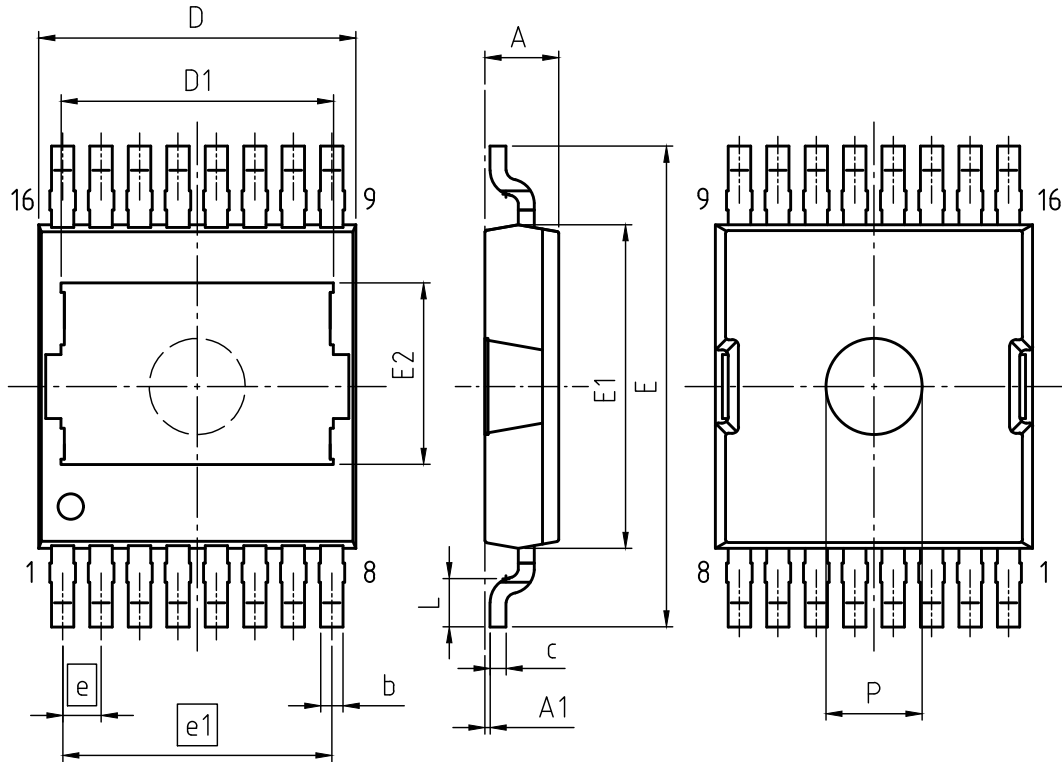


$V_{BR(DSS)}=f(T_j); I_D=1$ mA

Diagram Gate charge waveforms



5 Package Outlines



PACKAGE - GROUP NUMBER: PG-HDSOP-16-U01		
REVISION: 01	DATE: 18.12.2020	
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	2.25	2.35
A1	0.01	0.16
b	0.60	0.80
c	0.40	0.60
D	9.70	10.10
D1	8.20	8.40
E	14.80	15.20
E1	10.00	10.30
E2	5.57	5.77
e	1.20	
e1	8.40	
L	1.40	1.60
P	2.90	3.10

Figure 1 Outline PG-HDSOP-16, dimensions in mm

Revision History

IPTC026N12NM6

Revision: 2023-12-12, Rev. 2.0

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2023-12-12	Release of final version

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